April 2002

NDT2955

P-Channel Enhancement Mode Field Effect Transistor

General Description

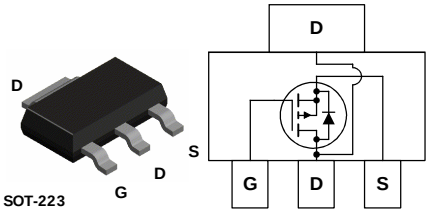
This 60V P-Channel MOSFET is produced using Fairchild Semiconductor's high voltage Trench process. It has been optimized for power management plications.

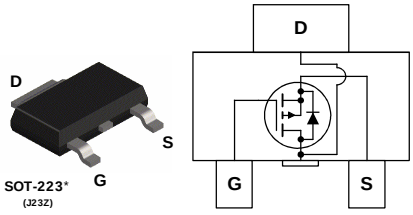
Applications

- DC/DC converter
- Power management

Features

- –2.5 A, –60 V. $R_{DS(ON)}$ = 300mΩ @ V_{GS} = –10 V
  $R_{DS(ON)}$ = 500mΩ @ V_{GS} = –4.5 V
- High density cell design for extremely low $R_{DS(ON)}$
- High power and current handling capability in a widely used surface mount package.





Absolute Maximum Ratings T_A=25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V_{DSS}	Drain-Source Voltage		–60	V
V_{GSS}	Gate-Source Voltage		±20	V
I_D	Drain Current – Continuous	(Note 1a)	–2.5	A
	– Pulsed		–15	
P_D	Maximum Power Dissipation	(Note 1a)	3.0	W
		(Note 1b)	1.3	
		(Note 1c)	1.1	
T_J, T_{STG}	Operating and Storage Junction Temperature Range		–55 to +150	°C

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	42	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	(Note 1)	12	

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
NDT2955	NDT2955	13''	12mm	2500 units

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Electrical Characteristics

T_A = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Avalanche Ratings						
W_{DSS}	Drain-Source Avalanche Energy	Single Pulse, V_{DD} = 30 V, I_D = 2.5 A			174	mJ
Off Characteristics						
BV_{DSS}	Drain–Source Breakdown Voltage	V_{GS} = 0 V, I_D = –250 µA	–60			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I_D = –250 µA, Referenced to 25°C		–60		mV/°C
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = –60 V, V_{GS} = 0 V			–10	µA
I_{GSSF}	Gate–Body Leakage, Forward	V_{GS} = –20 V, V_{DS} = 0 V			100	nA
I_{GSSR}	Gate–Body Leakage, Reverse	V_{GS} = –20 V, V_{DS} = 0 V			–100	nA
On Characteristics (Note 2)						
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = –250 µA	–2	–2.6	–4	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	I_D = –250 µA, Referenced to 25°C		5.7		mV/°C
$R_{DS(on)}$	Static Drain–Source On–Resistance	V_{GS} = –10 V, I_D = –2.5 A V_{GS} = –4.5 V, I_D = –2 A V_{GS}=–10 V, I_D =–2.5 A, T_J=125°C		95 163 153	300 500 513	mΩ
$I_{D(on)}$	On–State Drain Current	V_{GS} = –10 V, V_{DS} = –5 V	–12			A
g_{FS}	Forward Transconductance	V_{DS} = –10 V, I_D = –2.5 A		5.5		S
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS} = –30 V, V_{GS} = 0 V, f = 1.0 MHz		601		pF
C_{oss}	Output Capacitance			85		pF
C_{rss}	Reverse Transfer Capacitance			35		pF
Switching Characteristics (Note 2)						
$t_{d(on)}$	Turn–On Delay Time	V_{DD} = –30 V, I_D = –1 A, V_{GS} = –10 V, R_{GEN} = 6 Ω		12	21	ns
t_r	Turn–On Rise Time			10	20	ns
$t_{d(off)}$	Turn–Off Delay Time			19	34	ns
t_f	Turn–Off Fall Time			6	12	ns
Q_g	Total Gate Charge	V_{DS} = –30 V, I_D = –2.5 A, V_{GS} = –10 V		11	15	nC
Q_{gs}	Gate–Source Charge			2.4		nC
Q_{gd}	Gate–Drain Charge			2.7		nC
Drain–Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain–Source Diode Forward Current				–2.5	A
V_{SD}	Drain–Source Diode Forward Voltage	V_{GS} = 0 V, I_S = –2.5 A (Note 2)		–0.8	–1.2	V
t_{rr}	Diode Reverse Recovery Time	I_F = –2.5 A, d_{iF}/d_t = 100 A/µs		25		nS
Q_{rr}	Diode Reverse Recovery Charge			40		nC

Notes:

1. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.

a) 42°C/W when mounted on a 1in^2 pad of 2 oz copper

b) 95°C/W when mounted on a .0066 in^2 pad of 2 oz copper

c) 110°C/W when mounted on a minimum pad.

2. Pulse Test: Pulse Width < 300µs, Duty Cycle < 2.0%

Typical Characteristics

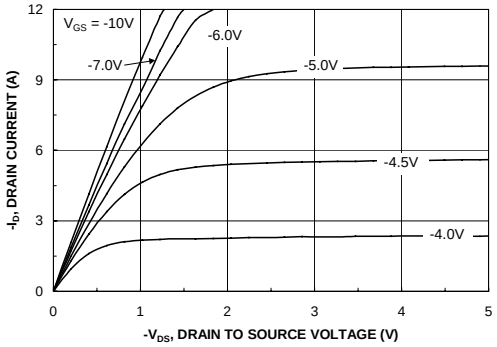

Figure 1. On-Region Characteristics.

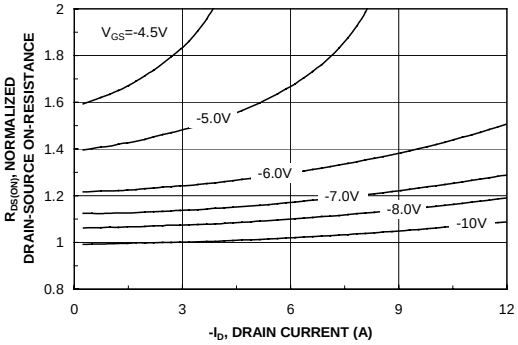

Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

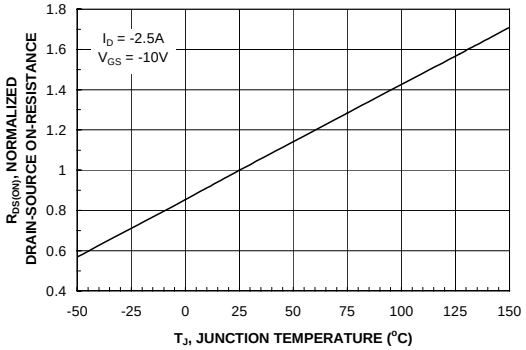

Figure 3. On-Resistance Variation withTemperature.

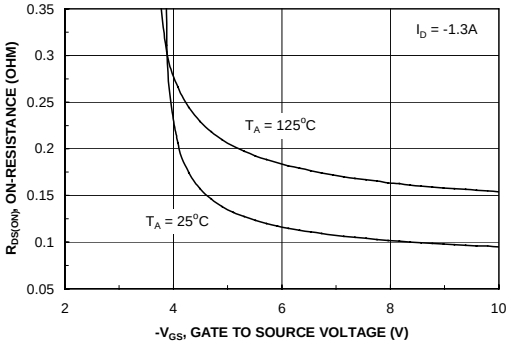

Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

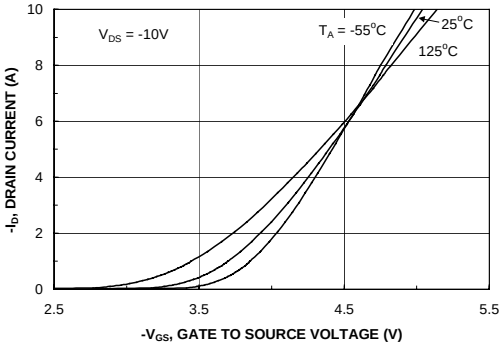

Figure 5. Transfer Characteristics.

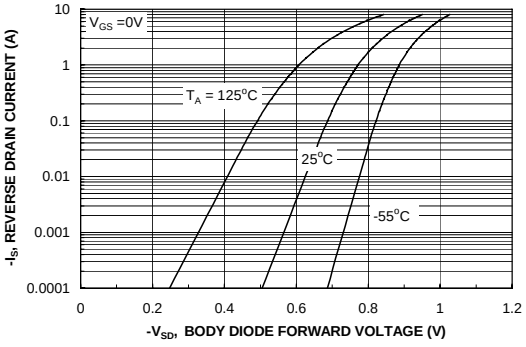

Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics

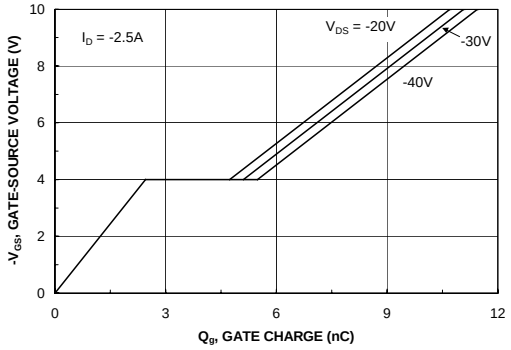

Figure 7. Gate Charge Characteristics.

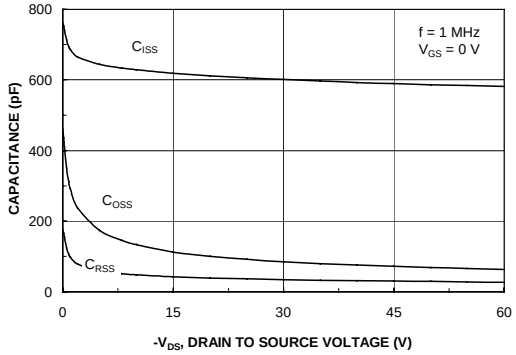

Figure 8. Capacitance Characteristics.

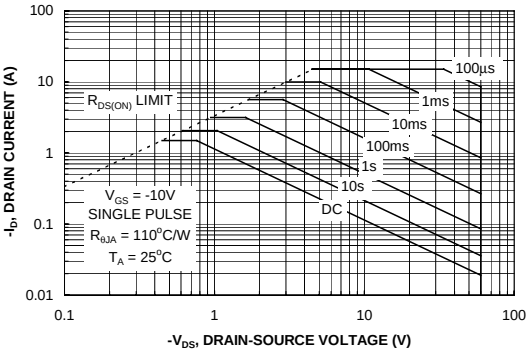

Figure 9. Maximum Safe Operating Area.

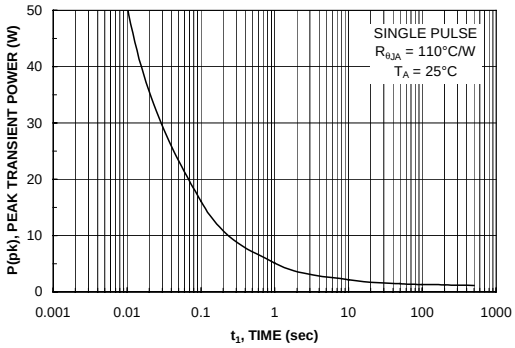

Figure 10. Single Pulse Maximum Power Dissipation.

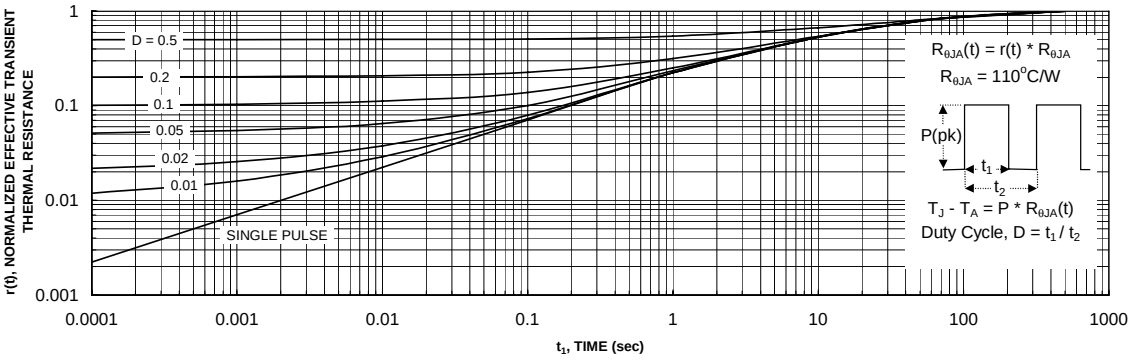

Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c.
Transient thermal response will change depending on the circuit board design.

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